



Surface Mount Gaskets and Grounding Pads

Our SMG gaskets can be used with many different types of board level shielding needs and when grounding points are required on your board. Form-in-Place gaskets can be eliminated by transferring the gasket to the board rather than to the thin edge of a casting or machined housing. No fear of damaging a thin Form-in-Place gasket during handling and assembly process. High speed SMT assembly of our tape and reel supplied gaskets make this a low cost reliable assembly option.

Part Numbers	Sizes						Packaging (parts per reel)	Core Materials	Cross Section (not to scale)
	Height		Width		Length				
SMG098118R-0.098	0.098	2.5	0.118	3	0.098	2.5	2100	Hollow High Temp. Sil. Sponge	
SMG118118R-0.079	0.118	3	0.118	3	0.079	2	1800	Hollow High Temp. Sil. Sponge	
SMG118118R-0.118	0.118	3	0.118	3	0.118	3	1800	Solid High Temp. Foam	
SMG118157R-0.197	0.118	3	0.157	4	0.197	5	1800	Hollow High Temp. Sil. Sponge	
SMG118197R-0.256	0.118	3	0.197	5	0.256	7	1500	Solid High Temp. Foam	
SMG256197R-0.118	0.256	6.5	0.197	5	0.118	3	1100	Solid High Temp. Foam	
SMG157256R-0.276	0.157	4	0.256	6.5	0.276	7	1200	Hollow High Temp. Sil. Sponge	
SMG236295R-0.157	0.236	6	0.295	7.5	0.157	4	1200	Hollow High Temp. Sil. Sponge	
SMG236354R-0.315	0.236	6	0.354	9	0.315	8	600	Hollow High Temp. Sil. Sponge	
SMG295197R-0.138	0.295	7.5	0.197	5	0.138	3.5	1000	Hollow High Temp. Sil. Sponge	

Black = inches Blue = mm Tolerance: +/- .019" (.48mm)

Applications

- Mobile Electronics
- Computers
- Integrated Circuits

Benefits

- Low Cost
- Suitable for Automated Placement
- Tape & Reel Packaging
- Off-The-Shelf
- Reflow Capabilities
- Low Compression Requirements
- Resilient

Material

- Outer Wrap
- Polyimide coated Sn/Cu



**SURFACE
MOUNT GASKETS**

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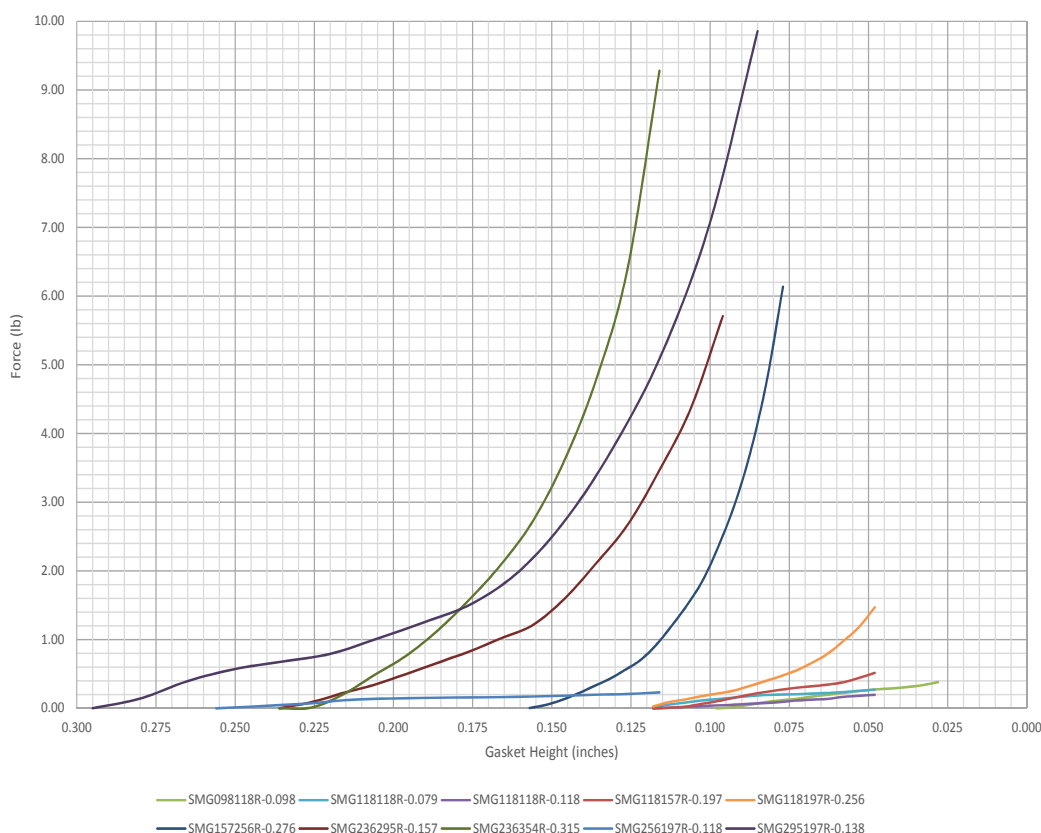
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Surface Mount Gaskets and Grounding Pads

Property	Method		Silicone Sponge	Polyurethane Foam
Outer Material	-		Polyimide coated Sn/Cu	Polyimide coated Sn/Cu
Color	-		Silver	Silver
Surface Resistance	ASTM D257		< 0.05 Ohm/in ²	< 0.05 Ohm/in ²
Hardness of Silicone	ASTM D2240		60 (Shore A)	20 (Shore C)
Deformation %	ASTM D5947	260°C, 30min	≤ 10%	≤ 10%
Resilience Ratio	ASTM D374	150°C, 100hrs, 20% compression	≥ 95%	≥ 85%
	ASTM D374	-40°C, 100hrs, 20% compression	≥ 95%	≥ 95%
	ASTM D374	85°C, 85% Rel. Humidity, 100hrs, 20% compression		
	ASTM D374	300 cycles, 20% compression		

Surface Mount Gasket - Force vs. Compression



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Outer Wrap

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Mouser Electronics

Authorized Distributor

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